



SOT855-4

plastic thermal enhanced thin quad flat package; 64 leads;
exposed die pad

8 February 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	HTQFP64
Package type industry code	HTQFP64
Package style descriptive code	HTQFP (thermal enhanced thin quad flat package)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MS-026
Mounting method type	S (surface mount)
Issue date	12-4-2011

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		9.9	-	10	10.1	mm
E	package width		9.9	-	10	10.1	mm
A	seated height		1	-	1.1	1.2	mm
A ₂	package height		0.95	-	1	1.05	mm
e	nominal pitch		-	-	0.5	-	mm
n ₂	actual quantity of termination		-	-	64	-	



2. Package outline

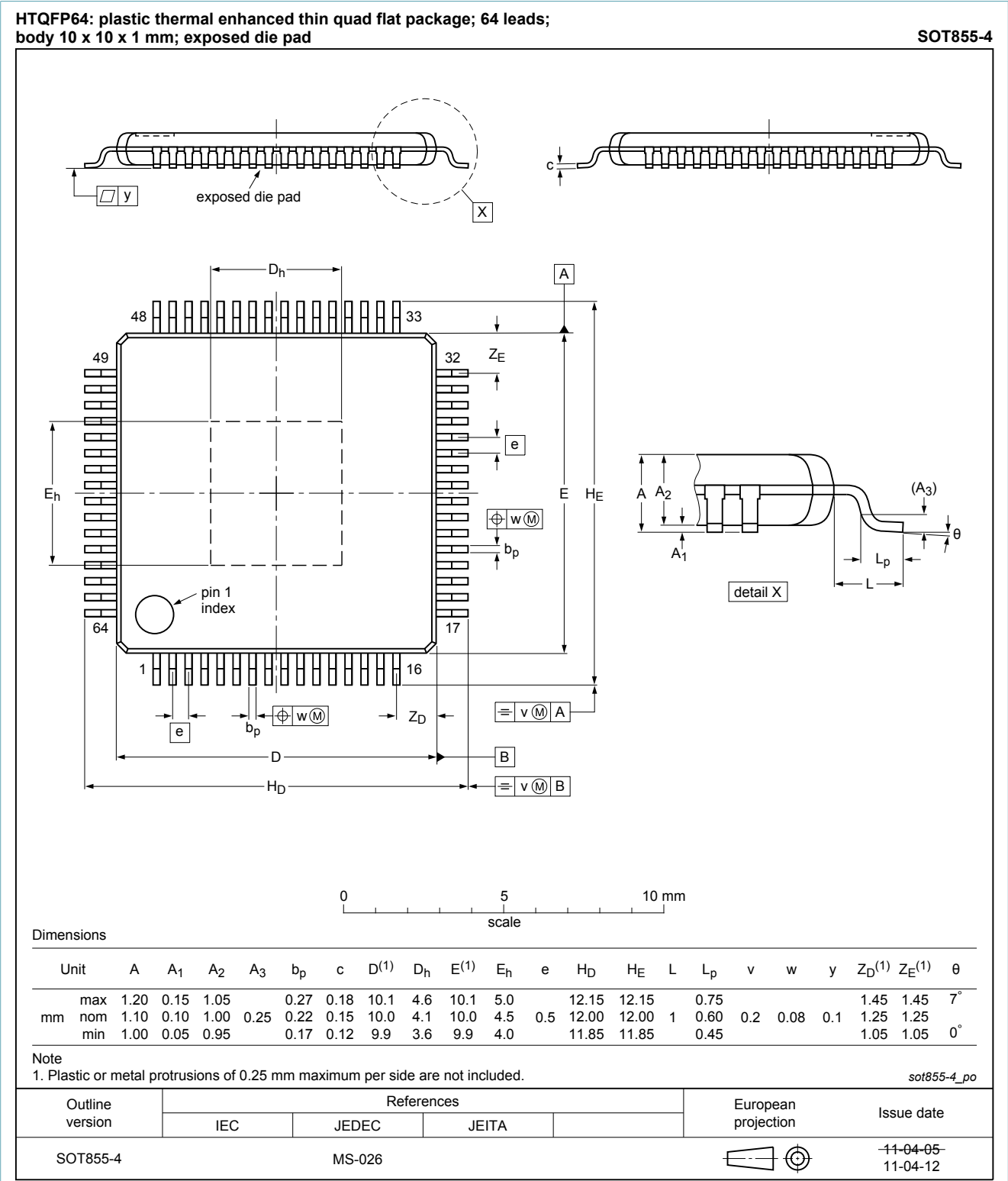


Fig. 1. Package outline HTQFP64 (SOT855-4)

3. Soldering

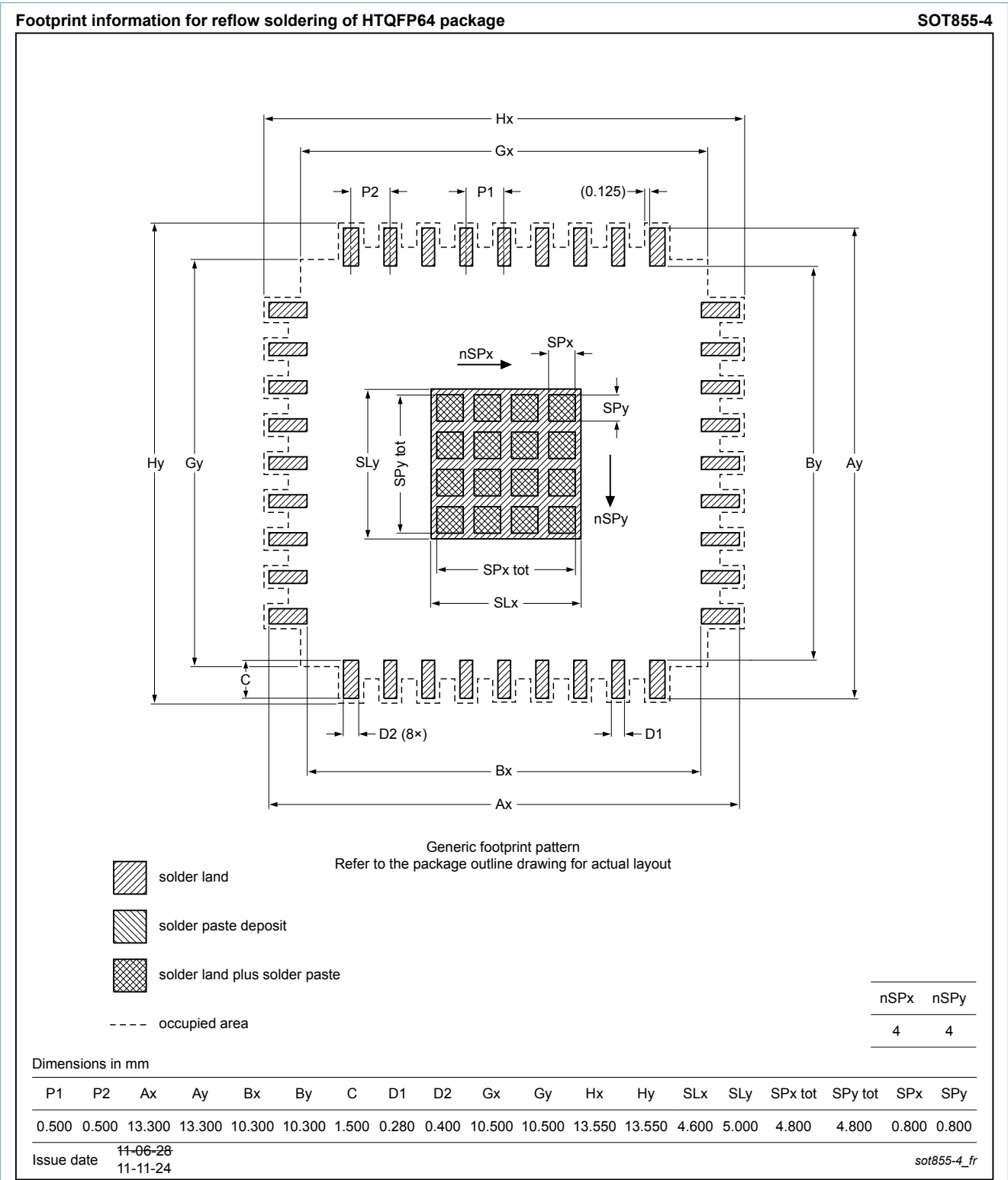


Fig. 2. Reflow soldering footprint for HTQFP64 (SOT855-4)

4. Legal information

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